

FEATURES

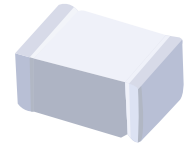
- | Surface Mounting Design 4.5*3.2*2.7mm

- | High Current Handling Capability 1000A @ 8/20 μs

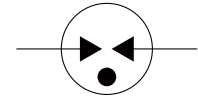
- | Low Capacitance and Insertion Loss

- | Quick Response and Long Service Life

- | Moisture sensitivity level: Level 1



4.5*3.2*2.7mm



Schematic Symbol

APPLICATION INFORMATION



- | Communication equipment.

- | Repeaters, Modems

- | Telephone Interface, Line cards.

- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	340-550	V
Impulse Spark-over Voltage	At 1kV/ μ s	for 99 % of measured values \leq 750	V
	At 1kV/ μ s	Typical values of distribution \leq 700	V
Impulse Discharge Current 2)	8/20 μ s	1000	A
Insulation Resistance	DC=100V	\geq 1	G Ω
Capacitance at 1MHz	V _{DC} =0.5V	\leq 1.0	pF
Operating And Storage Temperature		-40-125	$^{\circ}$ C

1) In ionized mode

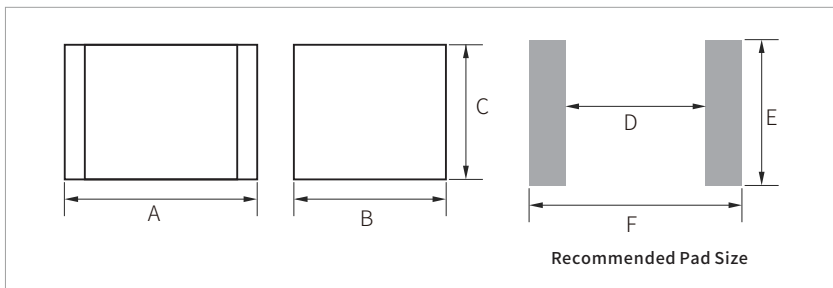
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 \pm 5 $^{\circ}$ C; Time of dip soldering: 10s, 1time

NOTE:Up-screen program can be specified by customer' s request via contacting Semiware service

DIMENSIONS AND RECOMMENDED SOLDERING PAD



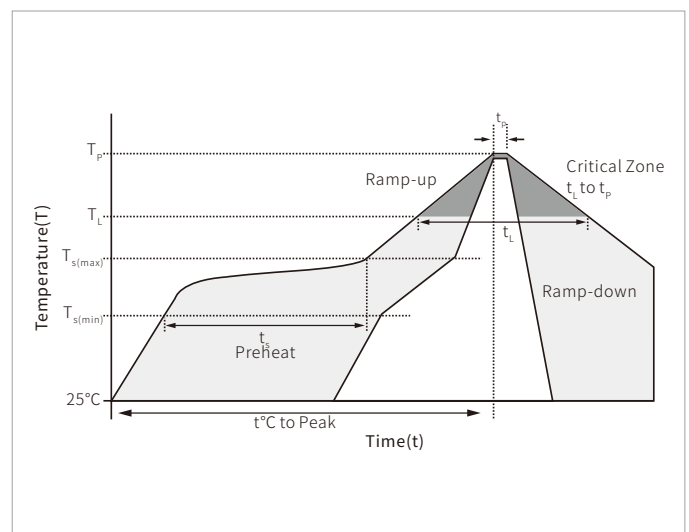
Ref.	mm
A	4.5 \pm 0.3mm
B	3.2 \pm 0.3mm
C	2.7 \pm 0.3mm
D	2.8mm
E	4.0mm
F	5.2mm

SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4-6 seconds

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max)(t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 °C
Time within 5°C of actual peak Temperature (t_p)		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
G4532B400A	4.5*3.2*2.7mm	2500PCS	13"

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